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ABSTRACT

**SEMICONDUCTOR MULTIPACKAGE MODULE INCLUDING
PROCESSOR AND MEMORY PACKAGE ASSEMBLIES**

A semiconductor multi-package module includes a processor and a plurality of memory packages mounted on a surface of the multipackage module substrate. In some embodiments the memory packages include stacked die packages, and in some embodiments the memory packages include stacked memory packages. In some embodiments the processor is situated at or near the center of the multipackage module substrate and the plurality of memory packages or of stacked memory package assemblies are situated on the multipackage module substrate adjacent the processor.